

# **ULTRA FAST RECOVERY POWER RECTIFIER**

### Absolute Maximum Ratings T<sub>C</sub>=25°C unless otherwise noted

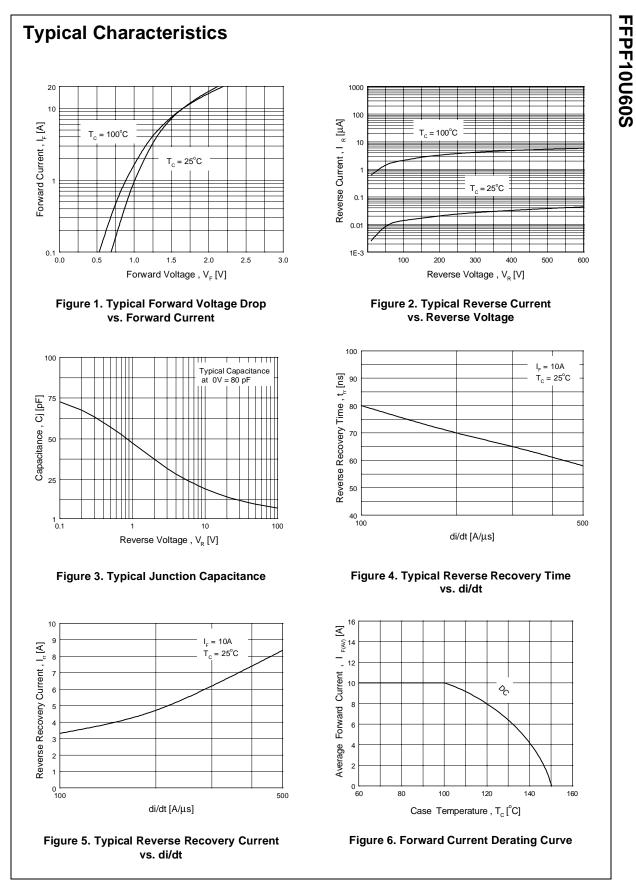
Symbol	Parameter	Value	Units
V <sub>RRM</sub>	Peak Repetitive Reverse Voltage	600	V
I <sub>F(AV)</sub>	Average Rectified Forward Current $@T_{C} = 100^{\circ}C$	10	A
I <sub>FSM</sub>	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	60	A
T <sub>J,</sub> T <sub>STG</sub>	Operating Junction and StorageTemperature	- 65 to +150	°C

## **Thermal Characteristics**

Symbol	Parameter	Value	Units	
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	2.5	°C/W	

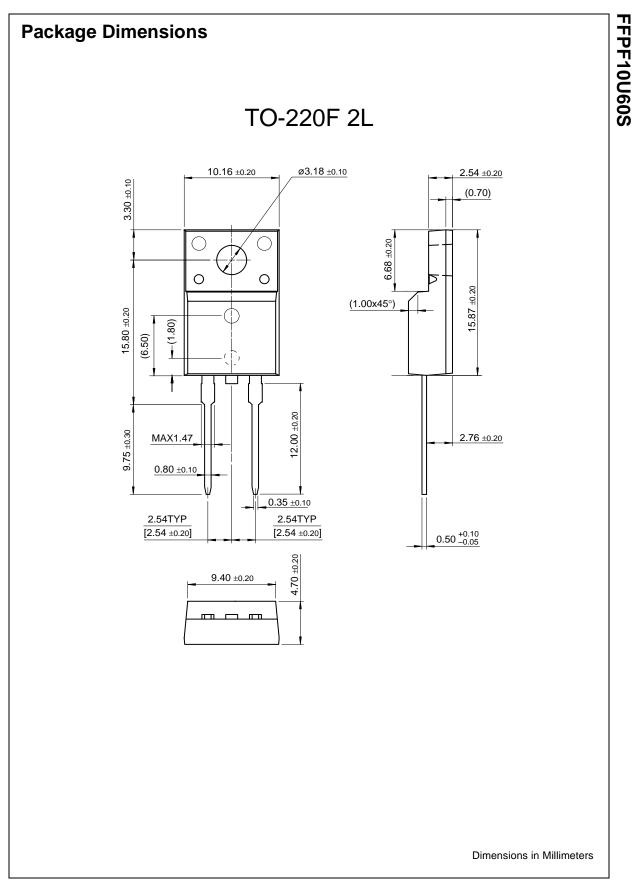
### Electrical Characteristics T<sub>C</sub>=25 °C unless otherwise noted

Symbol	Parameter		Min.	Тур.	Max.	Units
V <sub>FM</sub> *	Maximum Instantaneous Forward Voltage					V
	I <sub>F</sub> = 10A I <sub>F</sub> = 10A	T <sub>C</sub> = 25 °C T <sub>C</sub> = 100 °C			2.2 2.0	
RM *	Maximum Instantaneous Reverse Current @ rated V <sub>R</sub>	T <sub>C</sub> = 25 °C T <sub>C</sub> = 100 °C			5 50	μA
n Qu	Maximum Reverse Recovery Time Maximum Reverse Recovery Current Maximum Reverse Recovery Charge (I <sub>F</sub> =10A, di/dt = 200A/μs)				90 6 270	ns A nC
W <sub>AVL</sub>	Avalanche Energy		1.0			mJ



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QFET™ QS™ QT Optoelectronics<sup>™</sup> Quiet Series™ SuperSOT™-3 SuperSOT™-6 SuperSOT<sup>™</sup>-8 SyncFET™ TinyLogic™ UHC™

VCX™

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